

LM341/LM78MXX Series 3-Terminal Positive Voltage Regulators

General Description

The LM341 and LM78MXX series of three-terminal positive voltage regulators employ built-in current limiting, thermal shutdown, and safe-operating area protection which makes them virtually immune to damage from output overloads.

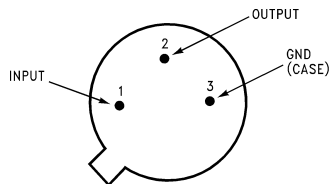
With adequate heatsinking, they can deliver in excess of 0.5A output current. Typical applications would include local (on-card) regulators which can eliminate the noise and degraded performance associated with single-point regulation.

Features

- Output current in excess of 0.5A
- No external components
- Internal thermal overload protection
- Internal short circuit current-limiting
- Output transistor safe-area compensation
- Available in TO-220, TO-39, and TO-252 D-PAK packages
- Output voltages of 5V, 12V, and 15V

Connection Diagrams

TO-39 Metal Can Package (H)

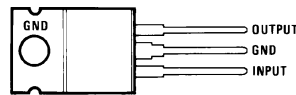


01048405

Bottom View

Order Number LM78M05CH, LM78M12CH or LM78M15CH
See NS Package Number H03A

TO-220 Power Package (T)

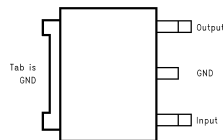


01048406

Top View

Order Number LM341T-5.0, LM341T-12, LM341T-15, LM78M05CT, LM78M12CT or LM78M15CT
See NS Package Number T03B

TO-252



01048419

Top View

Order Number LM78M05CDT
See NS Package Number TD03B

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Lead Temperature (Soldering, 10 seconds)	
TO-39 Package (H)	300°C
TO-220 Package (T)	260°C
Storage Temperature Range	-65°C to +150°C

Operating Junction Temperature

Range

-40°C to +125°C

Power Dissipation (Note 2)

Internally Limited

Input Voltage

 $5V \leq V_O \leq 15V$

35V

ESD Susceptibility

TBD

Electrical Characteristics

Limits in standard typeface are for $T_J = 25^\circ\text{C}$, and limits in **boldface type** apply over the -40°C to $+125^\circ\text{C}$ operating temperature range. Limits are guaranteed by production testing or correlation techniques using standard Statistical Quality Control (SQC) methods.

LM341-5.0, LM78M05C

Unless otherwise specified: $V_{IN} = 10V$, $C_{IN} = 0.33 \mu\text{F}$, $C_O = 0.1 \mu\text{F}$

Symbol	Parameter	Conditions	Min	Typ	Max	Units
V_O	Output Voltage	$I_L = 500 \text{ mA}$	4.8	5.0	5.2	V
		$5 \text{ mA} \leq I_L \leq 500 \text{ mA}$	4.75	5.0	5.25	
		$P_D \leq 7.5W, 7.5V \leq V_{IN} \leq 20V$				
$V_{R \text{ LINE}}$	Line Regulation	$7.2V \leq V_{IN} \leq 25V$			50	mV
					100	
$V_{R \text{ LOAD}}$	Load Regulation	$5 \text{ mA} \leq I_L \leq 500 \text{ mA}$			100	
I_Q	Quiescent Current	$I_L = 500 \text{ mA}$		4	10.0	mA
ΔI_Q	Quiescent Current Change	$5 \text{ mA} \leq I_L \leq 500 \text{ mA}$			0.5	
		$7.5V \leq V_{IN} \leq 25V, I_L = 500 \text{ mA}$			1.0	
V_n	Output Noise Voltage	$f = 10 \text{ Hz to } 100 \text{ kHz}$		40		μV
$\frac{\Delta V_{IN}}{\Delta V_O}$	Ripple Rejection	$f = 120 \text{ Hz}, I_L = 500 \text{ mA}$		78		dB
V_{IN}	Input Voltage Required to Maintain Line Regulation	$I_L = 500 \text{ mA}$	7.2			V
ΔV_O	Long Term Stability	$I_L = 500 \text{ mA}$			20	mV/khrs

Electrical Characteristics

Limits in standard typeface are for $T_J = 25^\circ\text{C}$, and limits in **boldface type** apply over the -40°C to $+125^\circ\text{C}$ operating temperature range. Limits are guaranteed by production testing or correlation techniques using standard Statistical Quality Control (SQC) methods. (Continued)

LM341-12, LM78M12C

Unless otherwise specified: $V_{IN} = 19\text{V}$, $C_{IN} = 0.33\ \mu\text{F}$, $C_O = 0.1\ \mu\text{F}$

Symbol	Parameter	Conditions	Min	Typ	Max	Units
V_O	Output Voltage	$I_L = 500\ \text{mA}$	11.5	12	12.5	V
		$5\ \text{mA} \leq I_L \leq 500\ \text{mA}$ $P_D \leq 7.5\text{W}$, $14.8\text{V} \leq V_{IN} \leq 27\text{V}$	11.4	12	12.6	
$V_{R\ \text{LINE}}$	Line Regulation	$14.5\text{V} \leq V_{IN} \leq 30\text{V}$	$I_L = 100\ \text{mA}$		120	mV
			$I_L = 500\ \text{mA}$		240	
$V_{R\ \text{LOAD}}$	Load Regulation	$5\ \text{mA} \leq I_L \leq 500\ \text{mA}$			240	
I_Q	Quiescent Current	$I_L = 500\ \text{mA}$		4	10.0	mA
ΔI_Q	Quiescent Current Change	$5\ \text{mA} \leq I_L \leq 500\ \text{mA}$ $14.8\text{V} \leq V_{IN} \leq 30\text{V}$, $I_L = 500\ \text{mA}$			0.5	
V_n	Output Noise Voltage	$f = 10\ \text{Hz to } 100\ \text{kHz}$		75		μV
$\frac{\Delta V_{IN}}{\Delta V_O}$	Ripple Rejection	$f = 120\ \text{Hz}$, $I_L = 500\ \text{mA}$		71		dB
V_{IN}	Input Voltage Required to Maintain Line Regulation	$I_L = 500\ \text{mA}$	14.5			V
ΔV_O	Long Term Stability	$I_L = 500\ \text{mA}$			48	mV/khrs

LM341-15, LM78M15C

Unless otherwise specified: $V_{IN} = 23\text{V}$, $C_{IN} = 0.33\ \mu\text{F}$, $C_O = 0.1\ \mu\text{F}$

Symbol	Parameter	Conditions	Min	Typ	Max	Units
V_O	Output Voltage	$I_L = 500\ \text{mA}$	14.4	15	15.6	V
		$5\ \text{mA} \leq I_L \leq 500\ \text{mA}$ $P_D \leq 7.5\text{W}$, $18\text{V} \leq V_{IN} \leq 30\text{V}$	14.25	15	15.75	
$V_{R\ \text{LINE}}$	Line Regulation	$17.6\text{V} \leq V_{IN} \leq 30\text{V}$	$I_L = 100\ \text{mA}$		150	mV
			$I_L = 500\ \text{mA}$		300	
$V_{R\ \text{LOAD}}$	Load Regulation	$5\ \text{mA} \leq I_L \leq 500\ \text{mA}$			300	
I_Q	Quiescent Current	$I_L = 500\ \text{mA}$		4	10.0	mA
ΔI_Q	Quiescent Current Change	$5\ \text{mA} \leq I_L \leq 500\ \text{mA}$ $18\text{V} \leq V_{IN} \leq 30\text{V}$, $I_L = 500\ \text{mA}$			0.5	
V_n	Output Noise Voltage	$f = 10\ \text{Hz to } 100\ \text{kHz}$		90		μV
$\frac{\Delta V_{IN}}{\Delta V_O}$	Ripple Rejection	$f = 120\ \text{Hz}$, $I_L = 500\ \text{mA}$		69		dB
V_{IN}	Input Voltage Required to Maintain Line Regulation	$I_L = 500\ \text{mA}$	17.6			V
ΔV_O	Long Term Stability	$I_L = 500\ \text{mA}$			60	mV/khrs

Note 1: Absolute maximum ratings indicate limits beyond which damage to the component may occur. Electrical specifications do not apply when operating the device outside of its rated operating conditions.

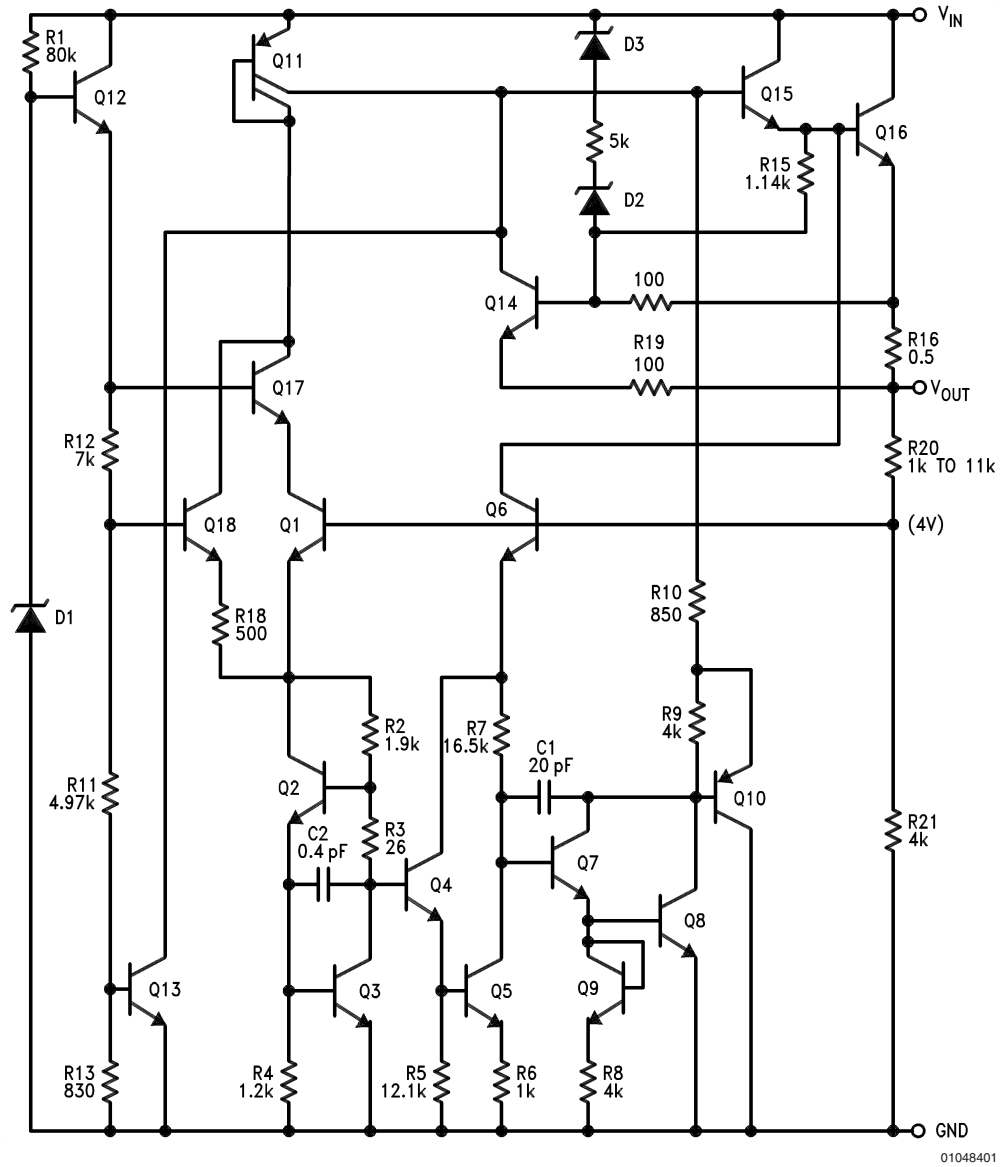
Note 2: The typical thermal resistance of the three package types is:

T (TO-220) package: $\theta_{(JA)} = 60\ ^\circ\text{C/W}$, $\theta_{(JC)} = 5\ ^\circ\text{C/W}$

H (TO-39) package: $\theta_{(JA)} = 120\ ^\circ\text{C/W}$, $\theta_{(JC)} = 18\ ^\circ\text{C/W}$

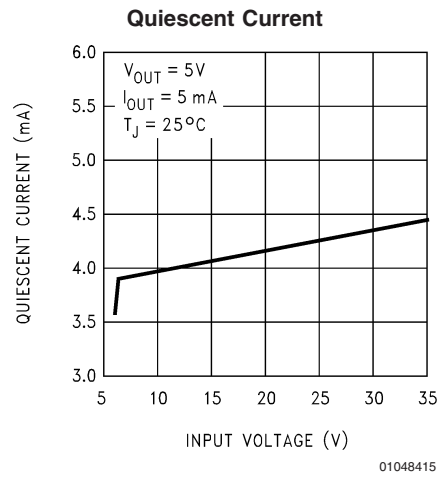
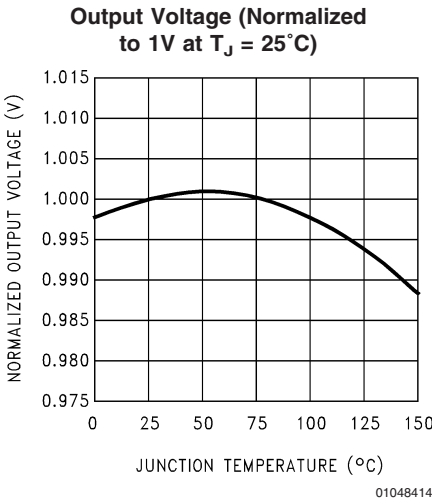
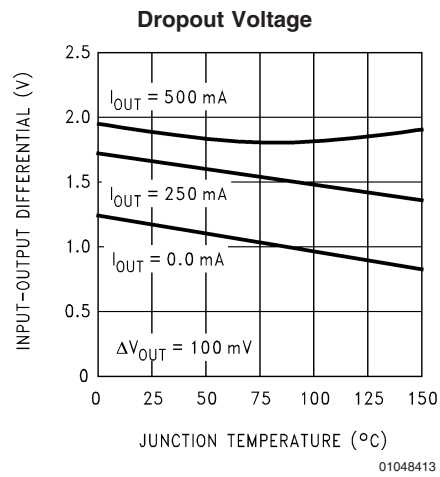
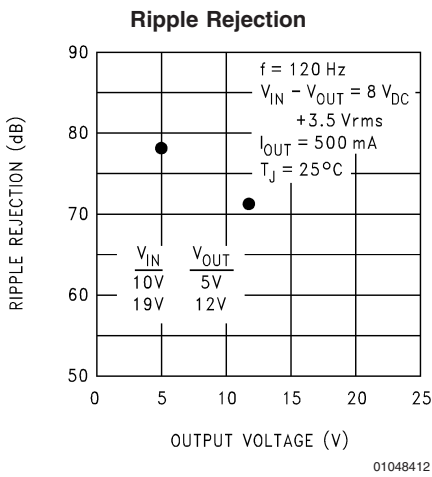
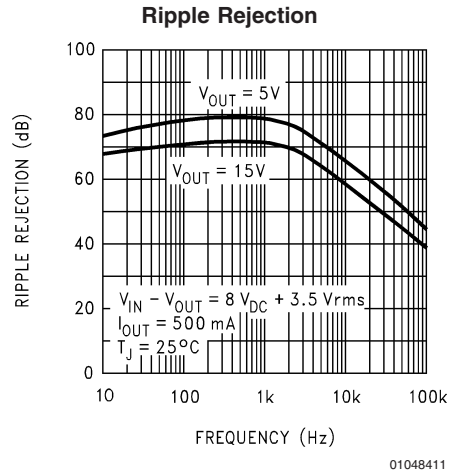
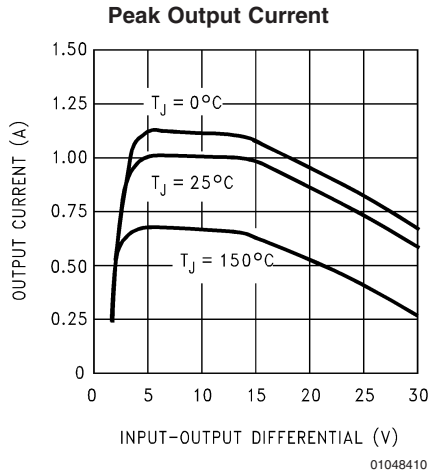
DT (TO-252) package: $\theta_{(JA)} = 92\ ^\circ\text{C/W}$, $\theta_{(JC)} = 10\ ^\circ\text{C/W}$

Schematic Diagram

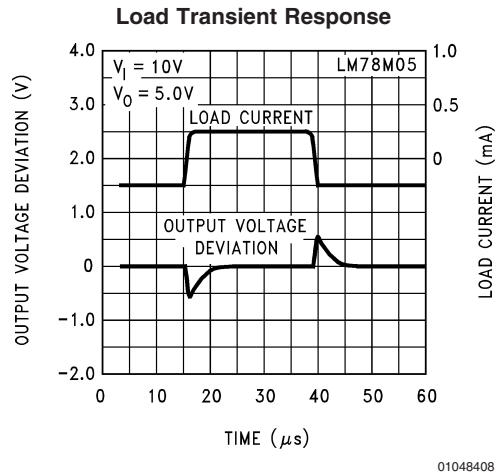
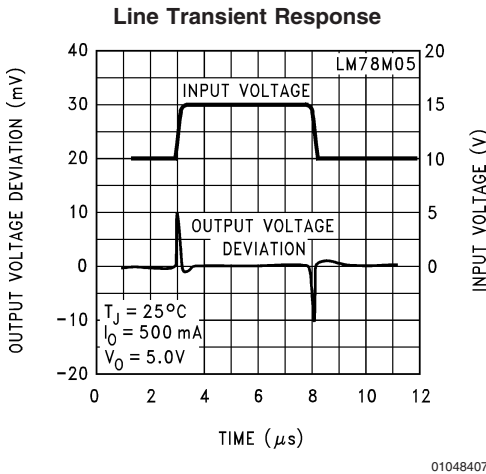
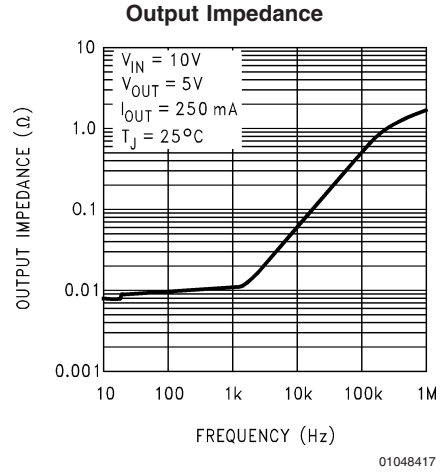
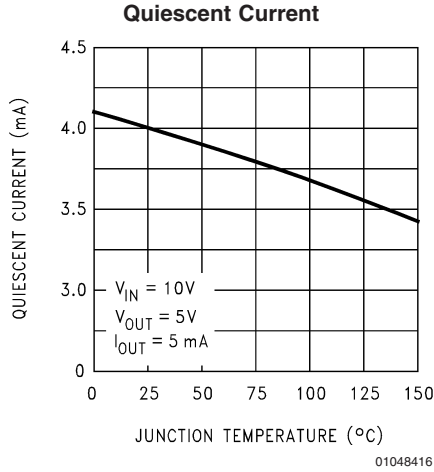


01048401

Typical Performance Characteristics



Typical Performance Characteristics (Continued)



Design Considerations

The LM78MXX/LM341XX fixed voltage regulator series has built-in thermal overload protection which prevents the device from being damaged due to excessive junction temperature.

The regulators also contain internal short-circuit protection which limits the maximum output current, and safe-area protection for the pass transistor which reduces the short-circuit current as the voltage across the pass transistor is increased.

Although the internal power dissipation is automatically limited, the maximum junction temperature of the device must be kept below +125°C in order to meet data sheet specifications. An adequate heatsink should be provided to assure this limit is not exceeded under worst-case operating conditions (maximum input voltage and load current) if reliable performance is to be obtained).

1.0 HEATSINK CONSIDERATIONS

When an integrated circuit operates with appreciable current, its junction temperature is elevated. It is important to quantify its thermal limits in order to achieve acceptable performance and reliability. This limit is determined by summing the individual parts consisting of a series of temperature rises from the semiconductor junction to the operating environment. A one-dimension steady-state model of con-

duction heat transfer is demonstrated in The heat generated at the device junction flows through the die to the die attach pad, through the lead frame to the surrounding case material, to the printed circuit board, and eventually to the ambient environment. Below is a list of variables that may affect the thermal resistance and in turn the need for a heatsink.

$R^{\theta JC}$ (Component Variables)	$R^{\theta CA}$ (Application Variables)
Leadframe Size & Material	Mounting Pad Size, Material, & Location
No. of Conduction Pins	Placement of Mounting Pad
Die Size	PCB Size & Material
Die Attach Material	Traces Length & Width
Molding Compound Size and Material	Adjacent Heat Sources
	Volume of Air
	Air Flow
	Ambient Temperature
	Shape of Mounting Pad

Application Information

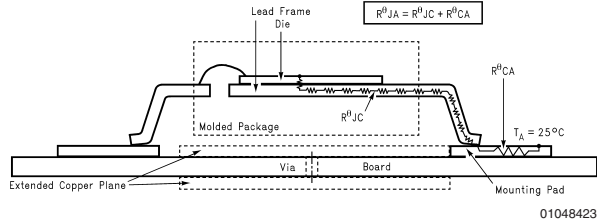


FIGURE 1. Cross-sectional view of Integrated Circuit Mounted on a printed circuit board. Note that the case temperature is measured at the point where the leads contact with the mounting pad surface

The LM78MXX/LM341XX regulators have internal thermal shutdown to protect the device from over-heating. Under all possible operating conditions, the junction temperature of the LM78MXX/LM341XX must be within the range of 0°C to 125°C. A heatsink may be required depending on the maximum power dissipation and maximum ambient temperature of the application. To determine if a heatsink is needed, the power dissipated by the regulator, P_D , must be calculated:

$$I_{IN} = I_L + I_G$$

$$P_D = (V_{IN} - V_{OUT}) I_L + V_{IN} I_G$$

shows the voltages and currents which are present in the circuit.

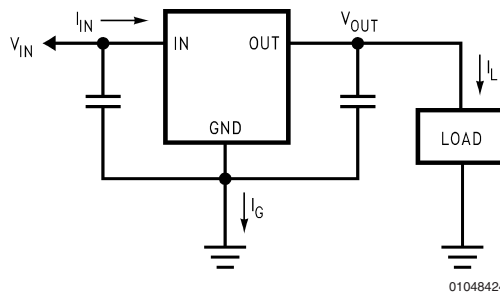


FIGURE 2. Power Dissipation Diagram

The next parameter which must be calculated is the maximum allowable temperature rise, $T_R(\text{max})$:

$$\theta_{JA} = T_R(\text{max})/P_D$$

If the maximum allowable value for θ_{JA} °C/W is found to be $\geq 60^\circ\text{C/W}$ for TO-220 package or $\geq 92^\circ\text{C/W}$ for TO-252 package, no heatsink is needed since the package alone will dissipate enough heat to satisfy these requirements. If the calculated value for θ_{JA} fall below these limits, a heatsink is required.

As a design aid, *Table 1* shows the value of the θ_{JA} of TO-252 for different heatsink area. The copper patterns that

we used to measure these θ_{JA} are shown at the end of the Application Note Section. reflects the same test results as what are in the *Table 1*

shows the maximum allowable power dissipation vs. ambient temperature for the TO-252 device. shows the maximum allowable power dissipation vs. copper area (in^2) for the TO-252 device. Please see AN1028 for power enhancement techniques to be used with TO-252 package.

Application Information (Continued)**TABLE 1. θ_{JA} Different Heatsink Area**

Layout	Copper Area		Thermal Resistance (θ_{JA} , °C/W) TO-252
	Top Side (in ²)*	Bottom Side (in ²)	
1	0.0123	0	103
2	0.066	0	87
3	0.3	0	60
4	0.53	0	54
5	0.76	0	52
6	1	0	47
7	0	0.2	84
8	0	0.4	70
9	0	0.6	63
10	0	0.8	57
11	0	1	57
12	0.066	0.066	89
13	0.175	0.175	72
14	0.284	0.284	61
15	0.392	0.392	55
16	0.5	0.5	53

*Tab of device attached to topside copper

Application Information (Continued)

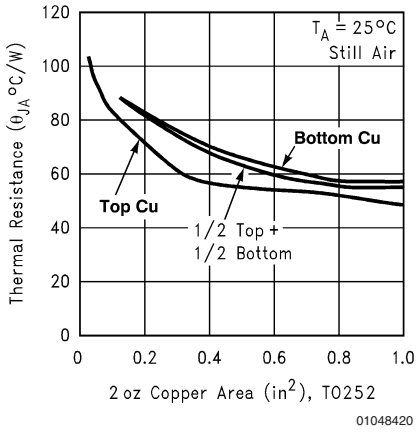


FIGURE 3. θ_{JA} vs. 2oz Copper Area for TO-252

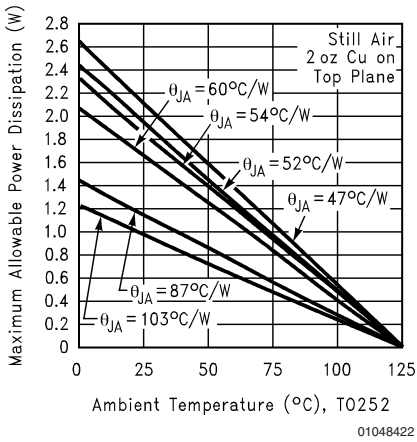


FIGURE 4. Maximum Allowable Power Dissipation vs. Ambient Temperature for TO-252

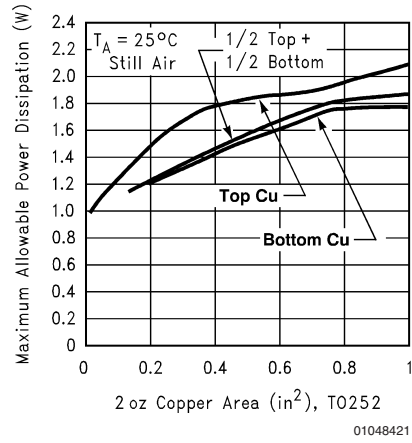
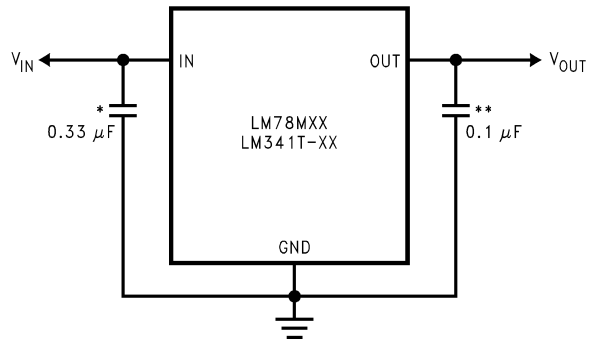


FIGURE 5. Maximum Allowable Power Dissipation vs. 2oz. Copper Area for TO-252

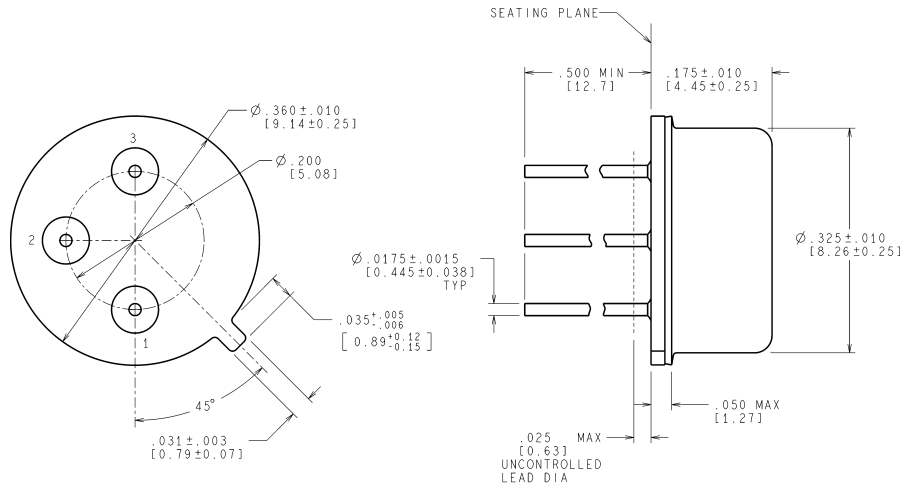
Typical Application



*Required if regulator input is more than 4 inches from input filter capacitor (or if no input filter capacitor is used).

**Optional for improved transient response.

Physical Dimensions inches (millimeters) unless otherwise noted

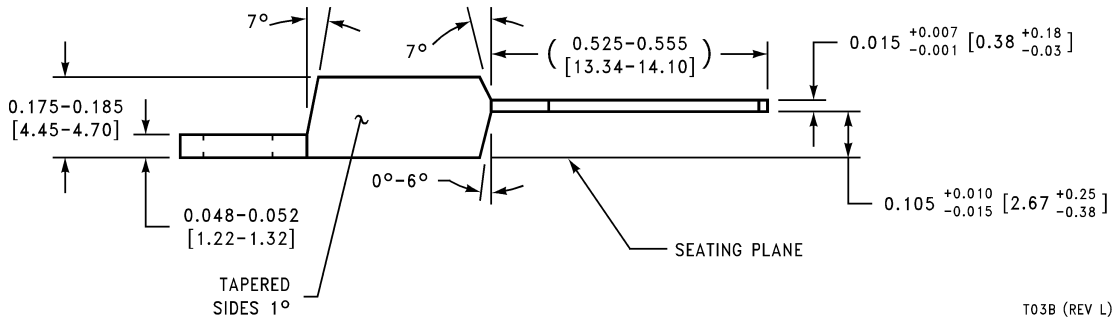
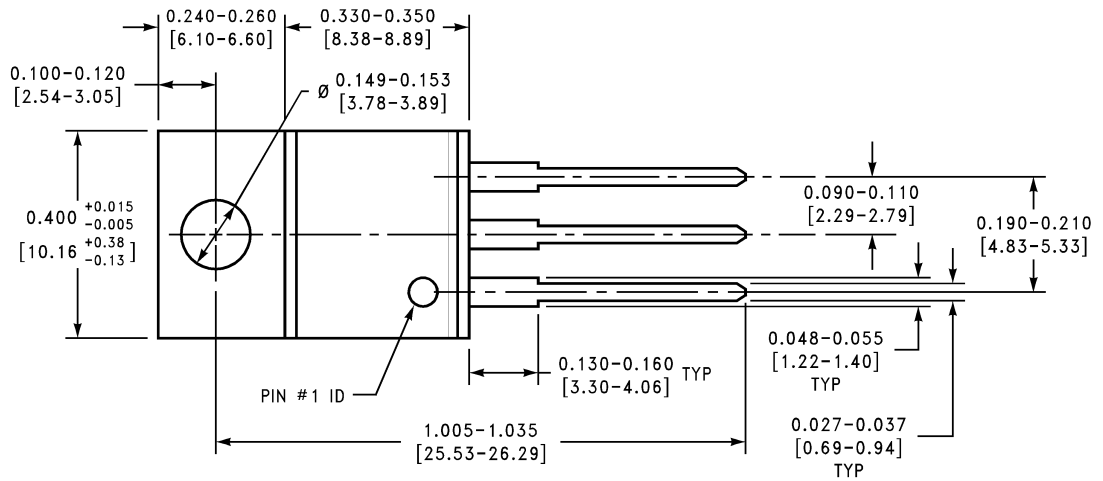


CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

MIL-PRF-38535
CONFIGURATION CONTROL

H03A (Rev D)

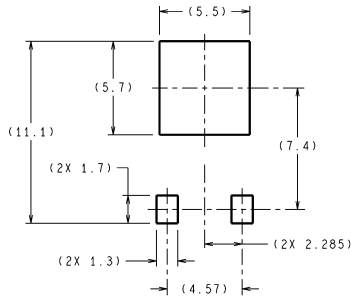
TO-39 Metal Can Package (H)
Order Number LM78M05CH, LM78M12CH or LM78M15CH
NS Package Number H03A



T03B (REV L)

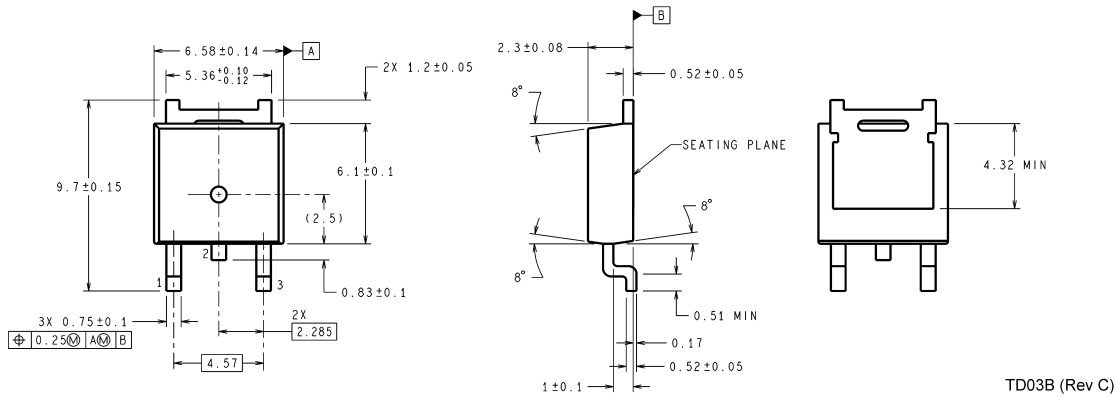
TO-220 Power Package (T)
Order Number LM341T-5.0, LM341T-12, LM341T-15, LM78M05CT, LM78M12CT or LM78M15CT
NS Package Number T03B

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



DIMENSIONS ARE IN MILLIMETERS

LAND PATTERN RECOMMENDATION



TD03B (Rev C)

TO-252
Order Number LM78M05CDT
NS Package Number TD03B

National does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and National reserves the right at any time without notice to change said circuitry and specifications.

For the most current product information visit us at www.national.com.

LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT AND GENERAL COUNSEL OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

BANNED SUBSTANCE COMPLIANCE

National Semiconductor manufactures products and uses packing materials that meet the provisions of the Customer Products Stewardship Specification (CSP-9-111C2) and the Banned Substances and Materials of Interest Specification (CSP-9-111S2) and contain no "Banned Substances" as defined in CSP-9-111S2.

Leadfree products are RoHS compliant.



National Semiconductor
Americas Customer
Support Center
 Email: new.feedback@nsc.com
 Tel: 1-800-272-9959

National Semiconductor
Europe Customer Support Center
 Fax: +49 (0) 180-530 85 86
 Email: europe.support@nsc.com
 Deutsch Tel: +49 (0) 69 9508 6208
 English Tel: +44 (0) 870 24 0 2171
 Français Tel: +33 (0) 1 41 91 8790

National Semiconductor
Asia Pacific Customer
Support Center
 Email: ap.support@nsc.com

National Semiconductor
Japan Customer Support Center
 Fax: 81-3-5639-7507
 Email: jpn.feedback@nsc.com
 Tel: 81-3-5639-7560

www.national.com

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Mobile Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Transportation and Automotive	www.ti.com/automotive
Video and Imaging	www.ti.com/video

TI E2E Community Home Page

e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2011, Texas Instruments Incorporated